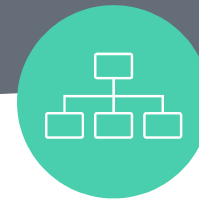
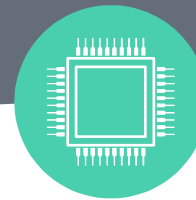


# Deep Learning

WaferMap Defect Pattern Recognition  
using improved DCN



第七組 |

RE6121045 侯登耀 數據所 P76121372 陳冠宇 資訊所

RE6125015 劉仁忠 數據所 P76124825 林柏志 資訊所

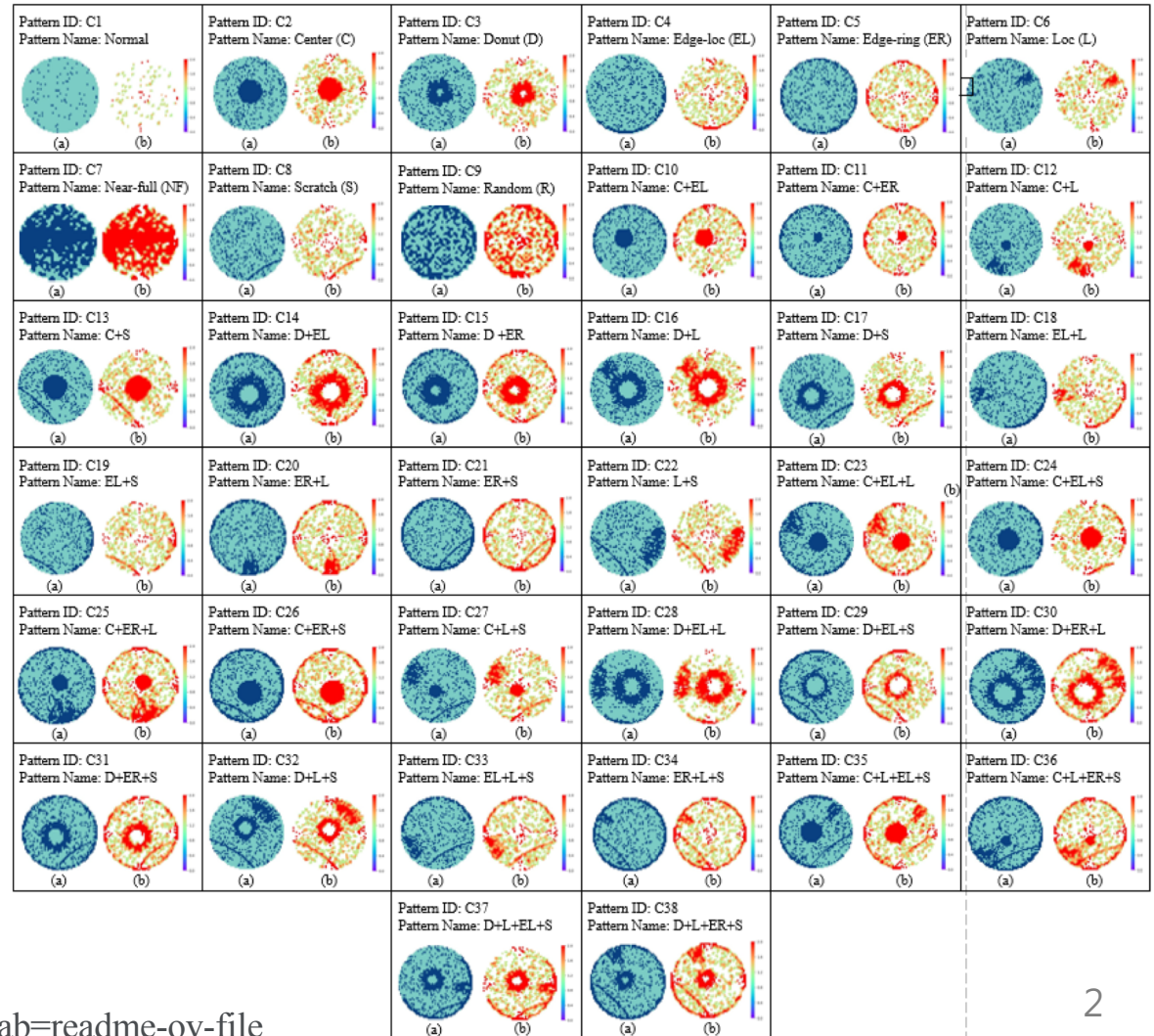
# WaferMap Defect Pattern Recognition using improved DCN

Dataset:

MixedWM38

- 38015 wafer maps

- 38 defect patterns

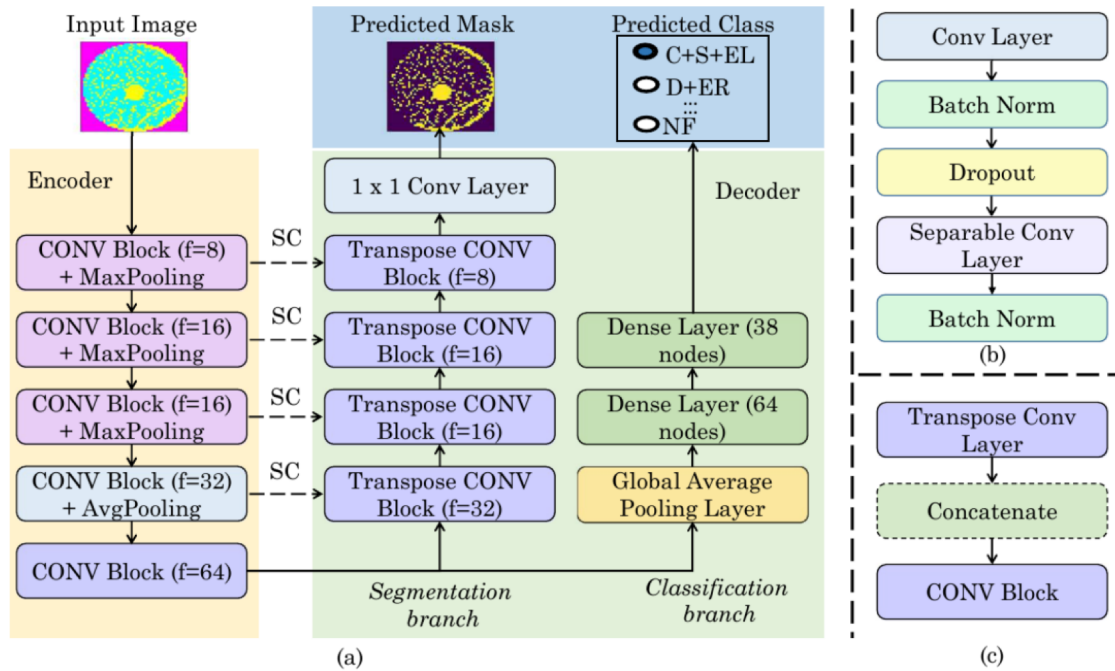


Dataset Source:

<https://github.com/Junliangwangdhu/WaferMap/tree/master?tab=readme-ov-file>

# SOTA Model - WaferSegClassNet

Nag et al. 2022. WaferSegClassNet



Encoder stage

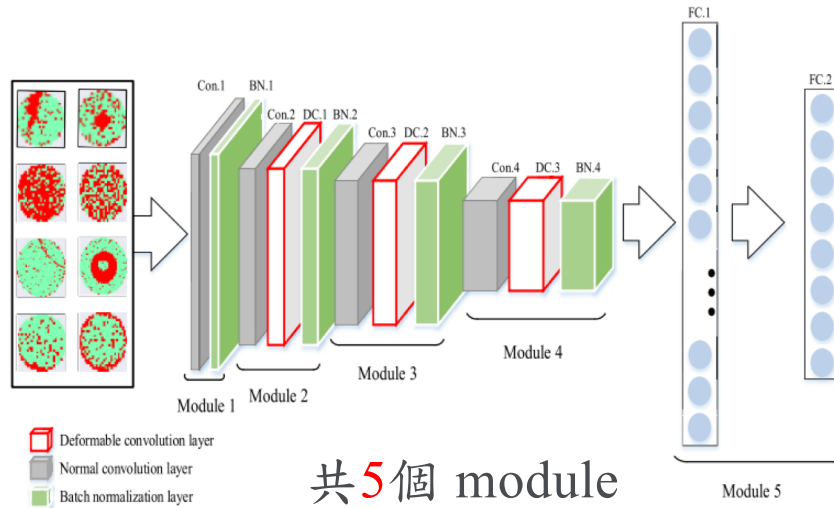
dual purpose  
Decoder stage

(b) CONV Block,  
(c) Transpose CONV block

Acc: 98.20%  
 Epochs: 50 (as accuracy didn't increase afterwards)  
 Running Time: +- 150 minutes  
 Advantage: High Accuracy  
 Disadvantage: Computational time

# Our Baseline Model - DCN

Wang et al. 2020. Deformable Convolutional Networks for Efficient Mixed-Type Wafer Defect Pattern Recognition



Loss Function: Binary Cross-entropy

Reproduce using Pytorch

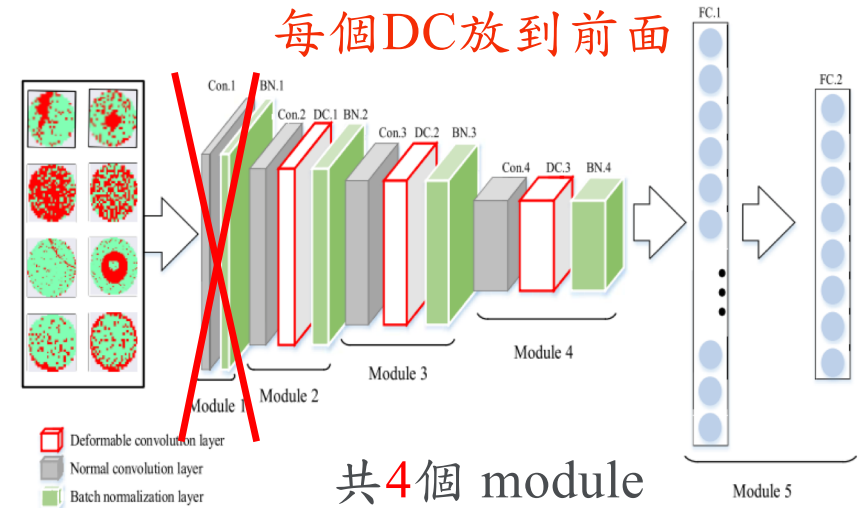
Acc: 94.4%

Epochs: 10

Time: +- 4 minutes

**Our modified model – Changes in network layer**

每個DC放到前面



Loss Function:  $\hat{y}$  MSE > 0.5 = 1, else 0

Reproduce using Pytorch

Acc: 96.4%

Epochs: 10

Time: +- 4 minutes

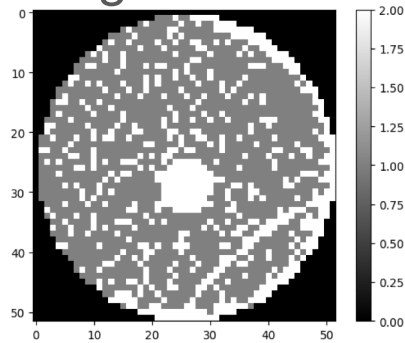
# Our Previous Model Comparisons

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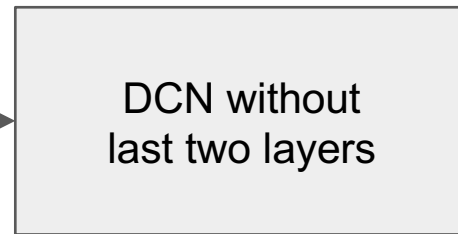
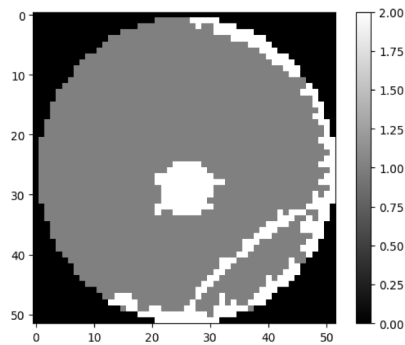
Model Version	Model Contents	Activation function	Epoch	Validation Accuracy
V1	Modify the model from Wang et al. 2020.	relu	10	96.60 %
V2	Modify Abnormal Values + V1	gelu	30	97.78 %
V3	Use CCA Denoised images + V2	gelu	30	94.00 %
V4	data augmentation ( vertical flip & horizontal flip ) + V2	gelu	30	97.92 %
V5	V1 + V3 (no data augmentation)	gelu	30	97.65 %

# Combined Model ( V5 )

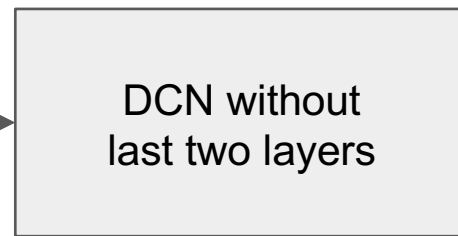
Original Data



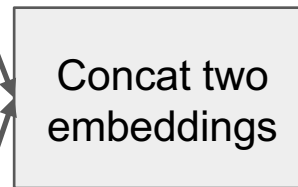
After CCA



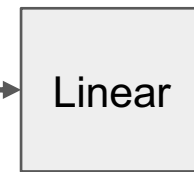
dim: 128



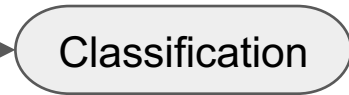
dim: 128



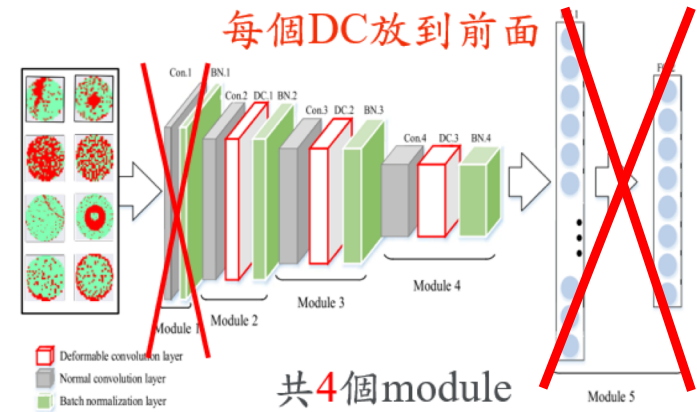
dim: 256



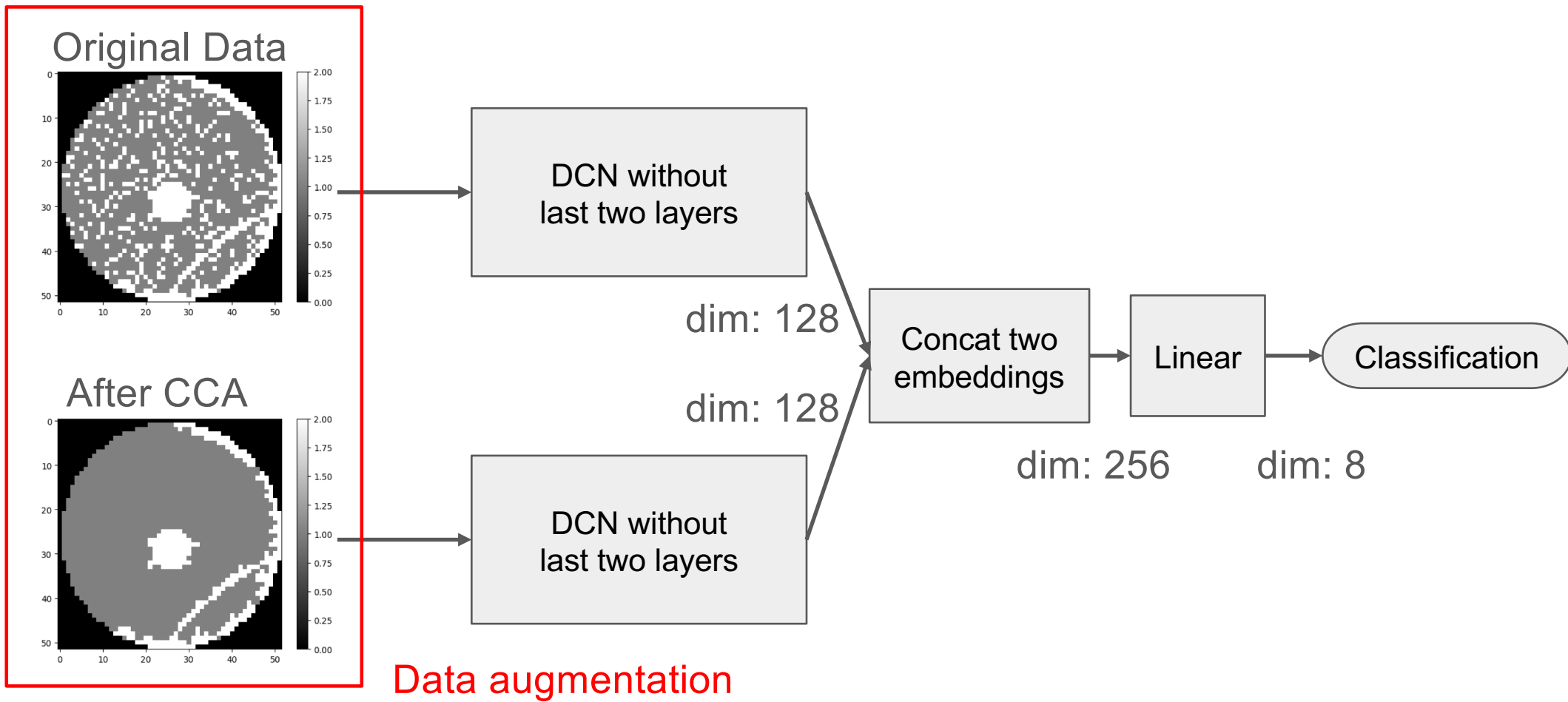
dim: 8



Our model – Changes in network layer



# Combined Model ( V6 )



# Explore Other Denoising Methods

CCA > 10

[[1. 1. 1.]  
[1. 1. 1.]  
[1. 1. 1.]]  
Threshold > 3

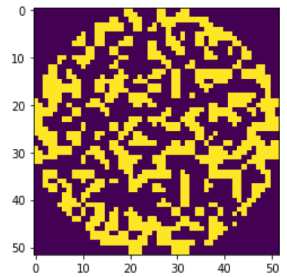
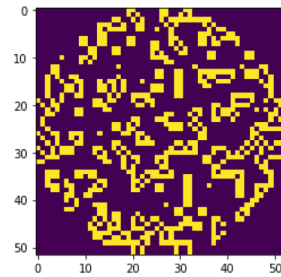
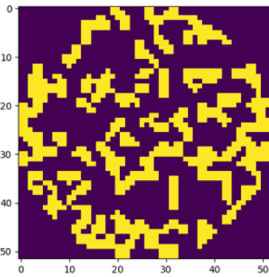
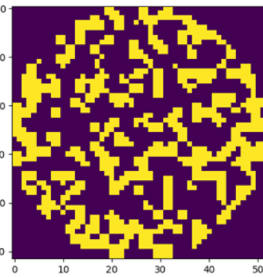
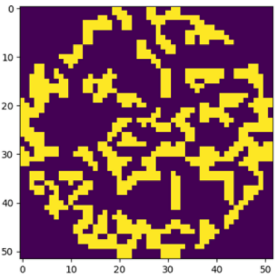
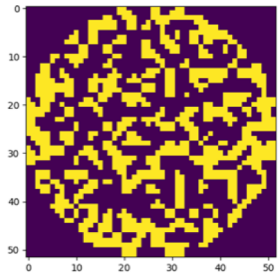
Threshold > 3  
CCA > 5

Laplace

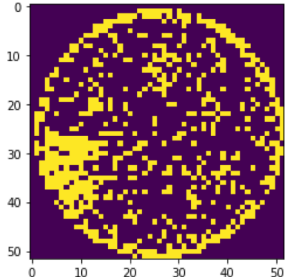
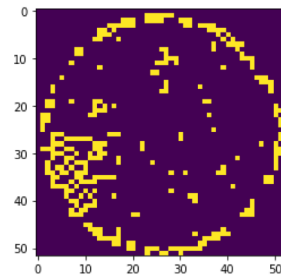
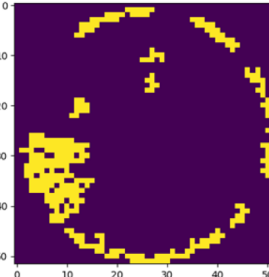
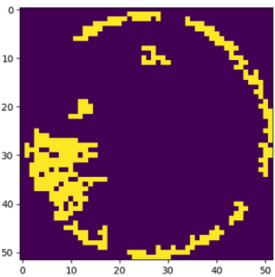
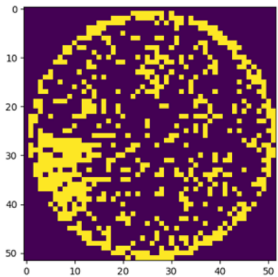
Threshold > 0.5

Baseline(V2)	CCA(V3)	Filter	Filter + CCA	Edge	C_mean
97.78	94.00	96.66	95.34	95.55	95.17

R  
A  
N  
D  
O  
M

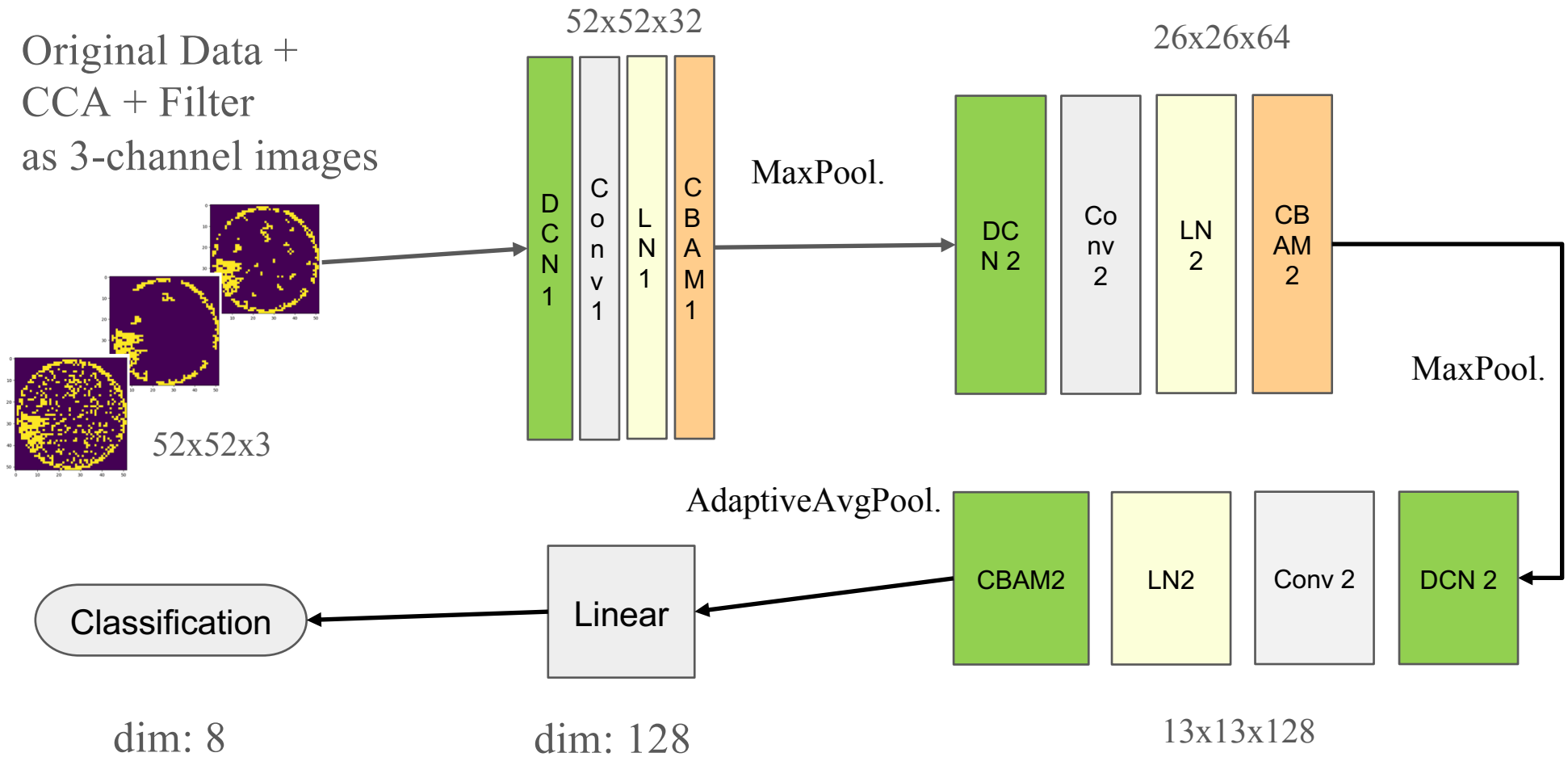


E  
D  
G  
E  
R  
I  
N  
G





# Channel-Combined Model ( V7 )



# Final Model Comparisons

Model	Validation Accuracy	Params	FLOPS
WSCN	98.20	90.00K	0.2M
Model V5	97.65	437.78K	1.817G
Model V6	98.17	437.77K	14.536G
Model V7	98.15	543.91K	2.740G

# Classwise Accuracy Results

Class	Accuracy				Precision				Recall			
	WSCN	Model V5	Model V6	Model V7	WSCN	Model V5	Model V6	Model V7	WSCN	Model V5	Model V6	Model V7
1	100	100	100	100	100	98	99	99	100	100	100	100
2	100	100	100	99.10	99	99	99	98	100	100	100	99
3	100	99.45	100	100	96	98	97	97	100	99	100	100
4	97	96.52	99.5	97.98	98	99	99	99	98	97	99	98
5	99	99.11	98.5	98.79	97	97	98	98	99	99	98	99
6	99	98.96	99	97.93	99	100	98	99	99	99	99	98
7	100	85.71	100	100	92	100	100	100	100	89	100	100
8	99	98.26	99.5	97.13	97	97	99	98	100	98	99	97
9	98	100	99.42	98.25	100	98	100	100	98	100	99	96

Class	Accuracy				Precision				Recall			
	WSCN	Model V5	Model V6	Model V7	WSCN	Model V5	Model V6	Model V7	WSCN	Model V5	Model V6	Model V7
<b>10</b>	98	98.08	98.5	97.66	98	97	98	99	99	98	98	98
11	100	100	99.5	100	99	98	99	98	100	100	99	100
12	99	98.94	99	97.88	99	97	97	97	100	99	99	98
<b>13</b>	99	100	99	98.51	98	97	98	99	100	100	99	99
<b>14</b>	94	97.52	99.5	97.21	100	99	98	99	95	98	99	97
<b>15</b>	99	99.5	97.5	100	98	99	97	97	99	100	97	100
<b>16</b>	95	98.85	99	96.55	100	97	98	98	95	99	99	97
17	100	98.63	98	100	96	98	98	98	100	99	98	100
<b>18</b>	99	98.93	98.5	98.97	99	96	97	96	100	99	98	99
<b>19</b>	97	96.74	99.5	98.97	99	99	100	98	98	97	99	99
<b>20</b>	96	96.61	98	99.53	99	98	98	99	96	96	98	100
21	100	99	100	99.56	98	97	99	99	100	99	100	100
<b>22</b>	97	97.98	97	96.86	99	98	98	95	97	98	97	97

Class	Accuracy				Precision				Recall			
	WSCN	Model V5	Model V6	Model V7	WSCN	Model V5	Model V6	Model V7	WSCN	Model V5	Model V6	Model V7
23	97	93.88	95	97.51	97	98	96	98	97	94	95	98
<b>24</b>	99	98.56	99	99.48	99	99	99	99	99	99	99	99
<b>25</b>	97	97.45	96.98	98.48	98	96	97	97	98	97	96	98
26	100	99.52	99.5	100	99	97	98	98	100	100	99	100
27	97	95.50	96	97.01	99	99	99	97	97	95	96	97
<b>28</b>	97	99.09	99	98.54	95	98	99	97	97	99	99	99
<b>29</b>	96	98.99	94.5	97.60	97	98	96	98	97	99	94	98
30	100	100	97.5	99.48	94	100	98	100	100	100	97	99
<b>31</b>	98	99.07	98	98.44	98	97	96	97	99	99	98	98
32	97	97	97	96.19	98	98	98	99	97	97	97	96
33	96	96.46	95.5	94.37	100	99	99	99	96	96	95	94
<b>34</b>	97	97.19	97	98.99	97	98	99	98	98	97	97	99

Class	Accuracy				Precision				Recall			
	WSCN	Model V5	Model V6	Model V7	WSCN	Model V5	Model V6	Model V7	WSCN	Model V5	Model V6	Model V7
<b>35</b>	94	93.75	96	95.05	100	97	98	98	95	94	96	95
<b>36</b>	97	95.67	98	96.79	98	98	98	99	98	96	98	97
<b>37</b>	95	93.58	94.5	95.81	99	99	100	99	95	94	94	96
<b>38</b>	95	97.12	99	97.95	99	98	99	99	95	97	99	98

Class	Accuracy				Precision				Recall			
	WSCN	Model V5	Model V6	Model V7	WSCN	Model V5	Model V6	Model V7	WSCN	Model V5	Model V6	Model V7
AVG (1 Defect)	99.00	97.55	99.54	98.64	97.25	98.44	98.78	99.33	99.33	97.89	99.33	98.44
AVG (2 Defect)	97.92	98.52	98.69	98.61	98.62	97.69	98.07	97.53	98.38	98.61	98.46	98.69
AVG (3 Defect)	97.58	97.73	97.08	97.41	97.58	98.08	97.83	97.25	97.92	97.67	96.83	97.25
AVG (4 Defect)	95.25	95.03	96.88	94.39	99.00	98	98.75	98.25	95.75	95.25	96.75	94
AVG (All Defect)	98.20	97.65	98.17	98.15	98.08	98.03	98.24	98.21	98.18	97.79	97.97	98.21

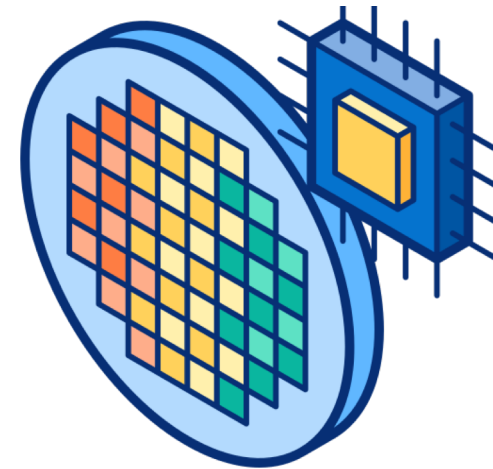
## Conclusion and Future Goals

- In this project, we modified the original DCN model and developed several useful models for the wafer map defect pattern classification problem.
- Although our models do not surpass the SOTA model in overall accuracy, they outperform in 21 out of 38 classes.
- We can focus on explainable AI, such as CAM-based models, in the future.



# References

- MixedWM38 Dataset
  - <https://github.com/Junliangwangdhu/WaferMap>
  - <https://www.kaggle.com/datasets/col1d7era/mixedtype-wafer-defect-datasets>
- Deformable Convolutional Networks for Efficient Mixed-Type Wafer Defect Pattern Recognition
  - <https://ieeexplore.ieee.org/document/9184890>
- WaferSegClassNet -- A Light-weight Network for Classification and Segmentation of Semiconductor Wafer Defects
  - <https://arxiv.org/abs/2207.00960>
- WM-811K
  - <https://www.kaggle.com/datasets/qingyi/wm811k-wafer-map/data>
- DCNv2
  - <https://arxiv.org/abs/2008.13535v2>



**Thanks for your attention.**

